



Materials Declaration

Package	PGA
Body Size	
Lead Count	68
Option	Pb-free

Combolid			
Item	% of Combolid	Weight (g)	PPM
Kovar	92.0	4.05E-01	58255
Nickel	4.0	1.76E-02	2533
Gold	4.0	1.76E-02	2533
Subtotal		4.40E-01	63320

Lid Frame			
Item	% of Lid Frame	Weight (g)	PPM
Gold	79.58	1.43 E-02	2061
Sn	20.42	3.68 E-03	529
Subtotal		1.80 E-02	2590

Ceramic Package			
Item	% of Ceramic	Weight (g)	PPM
Ceramics			
Al2O3	90.50	4.62 E+00	664215
Cr2O3	3.90	1.99 E-01	28624
SiO2	3.50	1.79 E-01	25688
TiO2	1.00	5.10 E-02	7339
CaO	0.60	3.06 E-02	4404
MgO	0.50	2.55 E-02	3670
Metallization			
Tungsten	99.37	5.12 E-01	73647
Molybdenum	0.63	3.24 E-03	467
Pin			
Iron	54.0	3.65 E-01	52455
Nickel	29.0	1.96 E-01	28170
Cobalt	17.0	1.15 E-01	16514
Coating 1			
Ag	85.0	6.38 E-02	9174
Cu	15.0	1.13 E-02	1619
Coating 2			
Nickel	92.0	3.13 E-02	4501
Cobalt	8.0	2.72 E-03	391
Subtotal		6.40 E+00	920878

Bond Wires			
Item	% of Wire	Weight (g)	PPM
Aluminum	100.0	2.00 E-02	2878

Chip			
Item	% of Chip	Weight (g)	PPM
Si	100.0	2.58 E-02	3713

Die Attach Paste			
Item	% of Die Attach Paste	Weight (g)	PPM
Silver Filler	80.0	7.20 E-03	1036
Cyanate ester resin	20.0	1.80 E-03	259
Subtotal		9.00 E-03	1295

External Pin Coating/Plating			
Item	% of Plating	Weight (g)	PPM
Gold	100.0	3.70 E-02	5325

Package Totals	
Weight (g)	PPM
6.95 E+00	1000000

Note: The information provided in this declaration are true to the best of ADI's knowledge. ADI derived most of the information listed in this declaration from documents provided by third parties, and assumes no liability to any inaccuracy of such information.



ADI Proprietary

